

Product End-of-Life Disassembly Instructions

Product Category: Notebooks and Tablet PCs

Marketing Name / Model [List multiple models if applicable.]

HP 630 Notebook PC

Name / Model #3

Name / Model #4

Name / Model #5

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

- 1.1 Items listed below are classified as requiring selective treatment.
- 1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	1
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0

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Components, parts and materials containing refractory ceramic fibers	
Components, parts and materials containing radioactive substances	

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Automatic crossing screw driver	Philip #1
Description #2	
Description #3	
Description #4	
Description #5	
3.0 Product Disassembly Process	

- 3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:
- Remove the Battery, and loosen screws on logic lower.
- Get HDD, ODD and memory.
- Remove KB, Pull out connecter.
- Remove C cover
- Pull out the DC IN cable, HDD connecter, ODD connecter, and USB Board cable, Remove Speaker cable from MB.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items

- Loosen screw on WLAN and remove antenna.
- Remove the MB, take down the thermal module and the CPU.
- Remove LCD module, tear down LCD Cover.
- Remove panel and camera

ontained in the product that require selective treatment (with descriptions and arrows identifying locations).						

Work Instructs

Document No.: Disassembly WI Step:1

Name Date: 2011-1-13 : Get Battery

Step:

- 1. Push the Battery switch and take off the battery.(Fig.1)
- 2. Loosen eight screws on Battery house and take off Memory Door.(Fig.2)

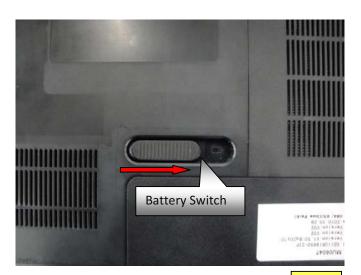
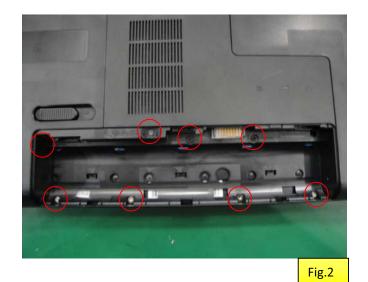


Fig.1



Fixture list(Fixture standard)	Qty	Fixture list(Fixture standard)	Qty
Cross Head of Screws Driver	1		

Point for attention: If finding some defects, notice the gaffer and assess.

PSG instructions for this template are available at EL-MF877-01

Work Instructs

Document No. : Disassembly WI Step : 2

Name : Get HDD/Memory/ODD Date : 2011-1-13

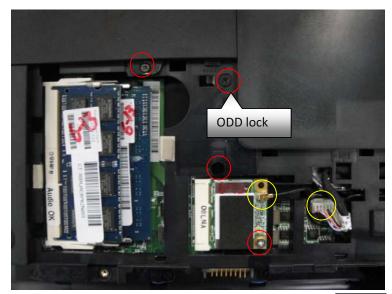


Fig.1

Step:

- Loosen four screws and pull out the WLAN cable and power cable.(Fig.1)
- 2. Take off Memory、WLAN、 HDD door and ODD.(Fig.1)
- 3. Loosen four screws and pull out HDD cable from MB. (Fig.2)

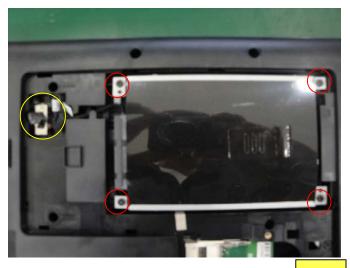


Fig.2

Fixture list(Fixture standard)	Qty	Fixture list(Fixture standard)	Qty
Cross Head of Screws Driver	1		

Work Instructs

Document No. : Disassembly WI Step : 3

Name : Get KB Date : 2011-1-13

Step:

- Loosen four screws on HDD door.(Fig.1)
- 2. Loosen ten screws.(Fig.2)
- 3. Take off the keyboard from top side, set at an angle of 45 degrees. (Fig.3)

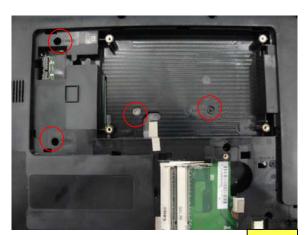
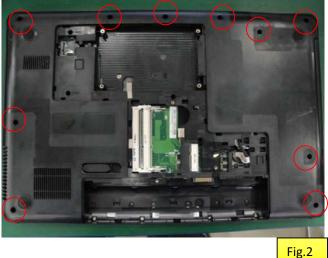


Fig.1





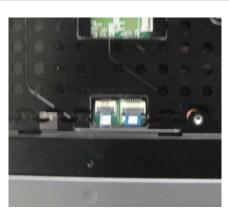
Fixture list(Fixture standard)	Qty	Fixture list(Fixture standard)	Qty
Cross Head of Screws Driver	1		

Work Instructs

Document No. : Disassembly WI Step : 4

Name : Remove C cover Date : 2011-1-13





Step:

1. Pull out the POWER BUTTON BOARD Cable.(Fig.1)

- 2. Remove the TB Cable.(Fig.2)
- 3. Loosen the screws and breakaway the logic upper along the arrowhead. (Fig.3)

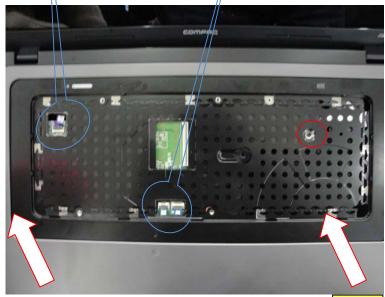


Fig.3

Fig.2

Fixture list(Fixture standard)	Qty	Fixture list(Fixture standard)	Qty
Cross Head of Screws Driver	1		

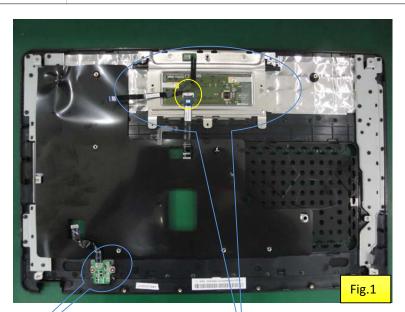
Work Instructs

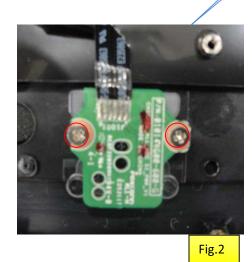
Document No. : Disassembly WI Step : 5

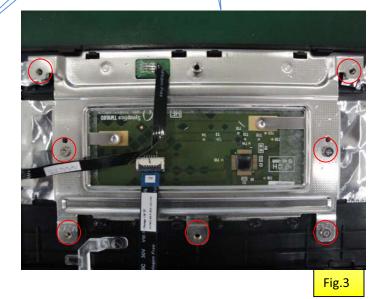
Name : Disassemble C cover Date : 2011-1-13

Step:

- 1. Pull out the TP cable. (Fig.1)
- Loosen two screws the and take off the POWER BUTTON BOARD.(Fig.2)
- 3. Loosen seven screws and remove the TP bracket.(Fig.3)







Fixture list(Fixture standard)	Qty	Fixture list(Fixture standard)	Qty
Cross Head of Screws Driver	1		

Work Instructs

Document No. :Disassembly WI Step : 6

Name :Get Mother Board Date : 2011-1-13

Step:

- 1. Take off RTC battery.(Fig.1)
- 2. Pull out LVDS/FAN cable/ Speaker cable/HDD cable/USB Board cable from MB.(Fig.1)
- Loosen the screw and remove USB Board. (Fig.2)
- 4. Loosen four screws and take off Speaker. (Fig.3)

5.Loosen the screw and Take off the MB. (Fig.1)

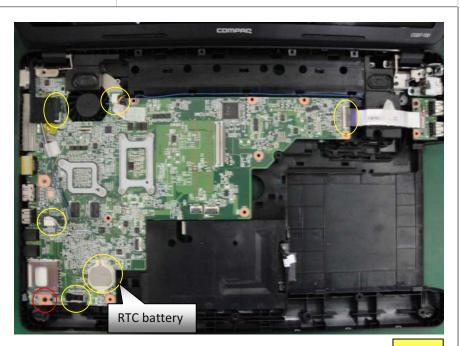
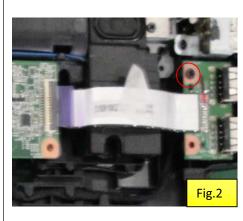
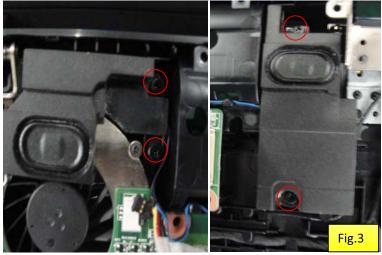


Fig.1



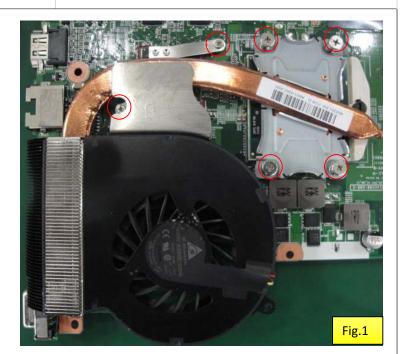


Fixture list(Fixture standard)	Qty	Fixture list(Fixture standard)	Qty
Cross Head of Screws Driver	1		

Work Instructs

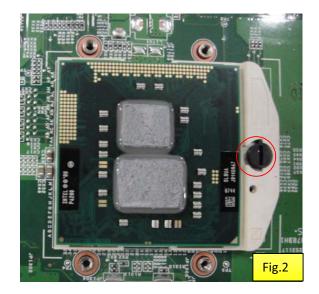
Document No. :Disassembly WI Step : 7

Name :Remove Thermal Module and CPU Date : 2011-1-13



Step:

- Loosen six screws and remove the Thermal Module.(Fig.1)
- 2. Turn the CPU lock 90 degree and get the CPU.(Fig.2)

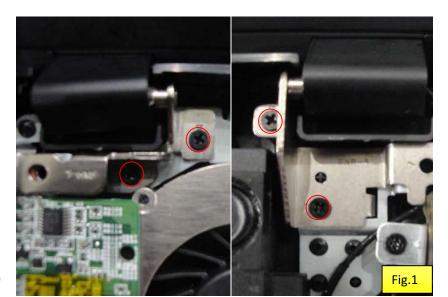


Fixture list(Fixture standard)	Qty	Fixture list(Fixture standard)	Qty
Cross Head of Screws Driver	1		

Work Instructs

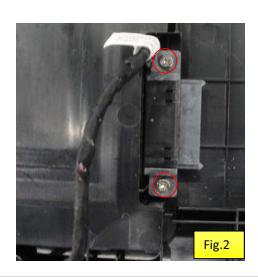
Document No. :Disassembly WI Step : 8

Name :Remove D cover Date : 2011-1-13



Step:

- Loosen four screws and take off the panel from D cover.(Fig.1)
- 2. Loosen two screws and remove HDD cable.(Fig.2)
- Loosen two screws and take off Power cable. (Fig.3)





Fixture list(Fixture standard)	Qty	Fixture list(Fixture standard)	Qty
Cross Head of Screws Driver	1		

Work Instructs

Document No. : Disassembly WI Step : 9

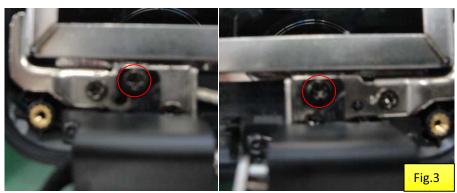
Name : Get LCD panel Date : 2011-1-13

COS7-100

Step:

- 1. Uncover two horned Mylar then loosen two screws.(Fig.1)
- 2. Breakaway the LCD bezel along the arrowhead.(Fig.2)
- 3. Loosen two screws and remove the Hinge Caps. (Fig.3)





Fixture list(Fixture standard)	Qty	Fixture list(Fixture standard)	Qty
Cross Head of Screws Driver	1		

Work Instructs

Document No. :Disassembly WI Step : 9

Name : Get LCD panel Date : 2011-1-13

Step:

- 4. Loosen six screws .(Fig.1)
- 5. Turn over LCD and pull out the LVDS connecter.(Fig.2)
- 6. Loosen six screws and remove the Hinges. (Fig.3)





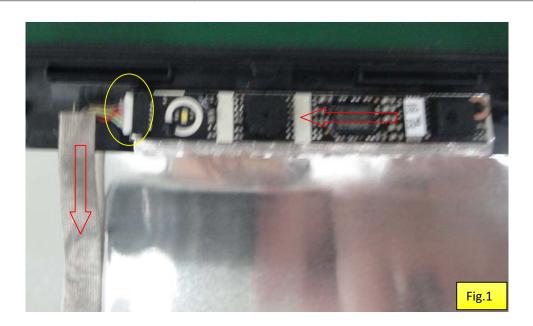


Fixture list(Fixture standard)	Qty	Fixture list(Fixture standard)	Qty
Cross Head of Screws Driver	1		

Work Instructs

Document No. :Disassembly WI Step : 10

Name Date: 2011-1-13 :Remove camera



Step:

- 1. Pull out the LVDS form camera and tear up the LVDS cable along the arrowhead. (Fig.1)
- 2. Tear up the camera from A cover along the arrowhead.(Fig.2)

Fixture list(Fixture standard)	Qty	Fixture list(Fixture standard)	Qty
Cross Head of Screws Driver	1		